

■ Features

- 0.56 Inch Three Digit Display
- Long lifetime operation
- IC compatible
- Low power dissipation
- Number of pins: 12

■ Applications

- Counting device
- Clock

■ Absolute Maximum Rating (Ta=25°C)

Item	Symbol	Value		Unit
		RA/R/YG/Y	B/G/W	
DC Forward Current	I _F	20	20	mA
Pulse Forward Current#	I _{FP}	100	100	mA
Reverse Voltage	V _R	5	5	V
Power Dissipation	P _t	44	66	mW
Operating Temperature	T _{opr}	-30 ~ +70		°C
Storage Temperature	T _{stg}	-40 ~ +85		°C
Lead Soldering Temperature(1.6mm from seating plane)	T _{sol}	260°C/5sec		°C

#Pulse width Max.10ms Duty ratio max 1/10

■ Electrical -Optical Characteristics (Ta=25°C)

Part Number	Color			V _F (V)			I _R (μA)	I _v (mcd)			λD(nm)		
				Min.	Typ.	Max.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.
				I _F =20mA			V _R =5V	I _F =20mA					
OSL30561-IW(LW)	White	W		2.8	3.3	4.0	10	-	65	-	CCT:8500-14000K		
OSL30561-IB(LB)	Blue	B	■	2.8	3.3	4.0	10	-	50	-	465	470	475
OSL30561-IG(LG)	Pure Green	G	■	2.8	3.3	4.0	10	-	200	-	515	525	530
OSL30561-IYG(LYG)	Yellow Green	YG	■	1.8	2.2	2.6	10	-	12	-	565	571	575
OSL30561-IY(LY)	Yellow	Y	■	1.8	2.1	2.5	10	-	60	-	585	590	595
OSL30561-IR(LR)	Red	R	■	1.8	2.1	2.5	10	-	26	-	625	630	640
OSL30561-IRA(LRA)	High Red	RA	■	1.8	2.1	2.5	10	-	100	-	620	625	630

*1 Tolerance of measurements of chromaticity coordinate is ±10%

*2 Tolerance of measurements of dominant wavelength is ±1nm

*3 Tolerance of measurements of luminous intensity is ±15%

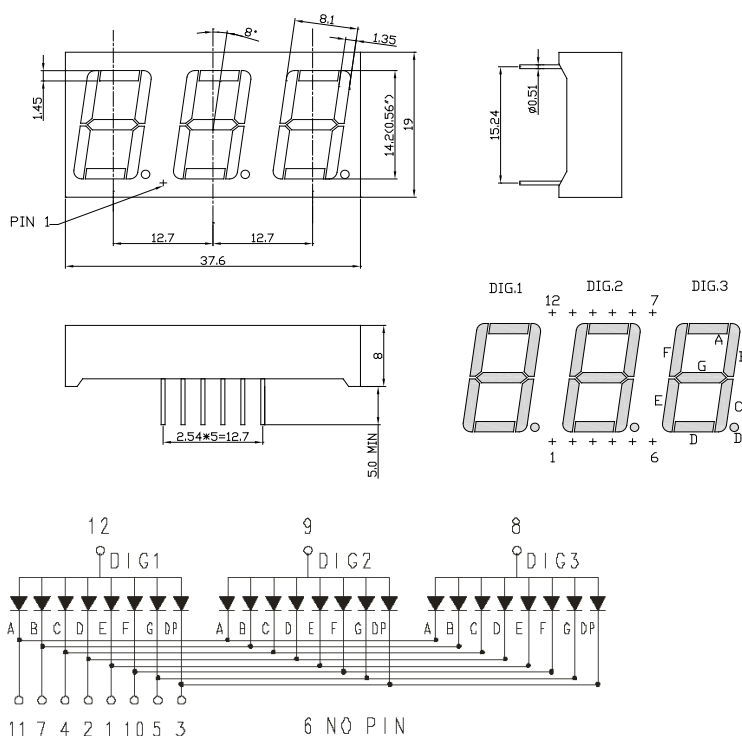
*4 Tolerance of measurements of forward voltage is ±0.1V

■ Photo



■ Package Dimensions and Pin Function

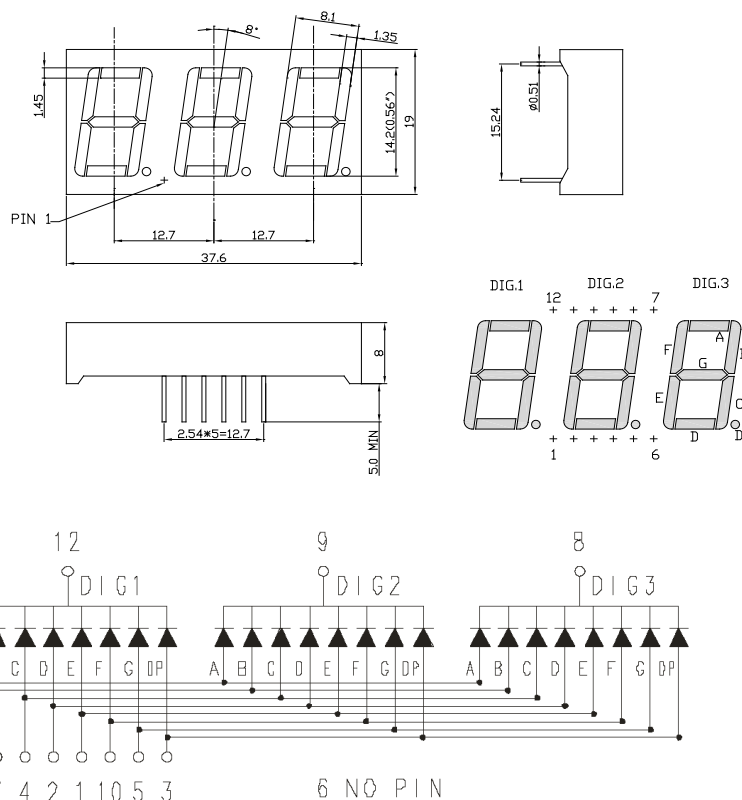
OSL30561-IX (Common Anode type)



Note:

- 1, Unit : mm (Tolerance: ± 0.25 mm unless otherwise noted)
- 2, The slope angle of any PIN may be $\pm 5.0^\circ$ Max

OSL30561-LX (Common Cathode type)



Note:

- 1, Unit : mm (Tolerance: ± 0.25 mm unless otherwise noted)
- 2, The slope angle of any PIN may be $\pm 5.0^\circ$ Max

LAMP APPLICATION (PB FREE SOLDERJING)

Apply to Display (DIP) SERIES.

Description:

(1) Manual soldering (Solder Iron)

- (1.1) Temperature at tip of the iron: 350°C Max.
- (1.2) It's banned to load any stress on the resin during soldering.
- (1.3) Soldering time: 3sec.Max.(one time only.)
- (1.4) Leave 3mm of minimum distance from the base of the epoxy.

(2) Dip Soldering (Wave Soldering-Solder Bath)

- (2.1) Leave 3mm of minimum distance from the base of the epoxy.
Soldering beyond the base of the tie bar (stand off) is recommended.
- (2.2) When soldering, do not put stress on the Display during heating.
- (2.3) Cutting the lead frames at high temperatures may cause LED failure.
- (2.4) Never take next process until the component is cooled down to room temperature after reflow.
- (2.5) After soldering, do not warp the circuit board.
- (2.6) The recommended dip soldering profile is the following.

